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## 1. Electrical Specifications

**Table 1. Recommended Operating Conditions**

| Parameter                     | Symbol     | Test Condition                    | Min  | Typ | Max  | Unit |
|-------------------------------|------------|-----------------------------------|------|-----|------|------|
| Ambient Operating Temperature | $T_A$      |                                   | -40  | —   | 85   | °C   |
| Supply Voltage Range*         | $V_{DD}$   | LVDS, CML                         | 1.71 | 1.8 | 1.89 | V    |
|                               |            |                                   | 2.38 | 2.5 | 2.63 | V    |
|                               |            |                                   | 2.97 | 3.3 | 3.63 | V    |
|                               |            | LVPECL, low power LVPECL, LVC MOS | 2.38 | 2.5 | 2.63 | V    |
|                               |            |                                   | 2.97 | 3.3 | 3.63 | V    |
|                               |            | HCSL                              | 2.97 | 3.3 | 3.63 | V    |
| Output Buffer Supply Voltage* | $V_{DDOX}$ | LVDS, CML, LVC MOS                | 1.71 | 1.8 | 1.89 | V    |
|                               |            |                                   | 2.38 | 2.5 | 2.63 | V    |
|                               |            |                                   | 2.97 | 3.3 | 3.63 | V    |
|                               |            | LVPECL, low power LVPECL          | 2.38 | 2.5 | 2.63 | V    |
|                               |            |                                   | 2.97 | 3.3 | 3.63 | V    |
|                               |            | HCSL                              | 2.97 | 3.3 | 3.63 | V    |

**\*Note:** Core supply  $V_{DD}$  and output buffer supplies  $V_{DDOX}$  are independent. LVC MOS clock input is not supported for  $V_{DD} = 1.8V$  but is supported for LVC MOS clock output for  $V_{DDOX} = 1.8V$ . LVC MOS outputs at 1.5V and 1.2V can be supported via a simple resistor divider network. See “2.8.1. LVC MOS Output Termination To Support 1.5 V and 1.2 V”

**Table 2. Input Clock Specifications**

( $V_{DD} = 1.8V \pm 5\%$ ,  $2.5V \pm 5\%$ , or  $3.3V \pm 10\%$ ,  $T_A = -40$  to  $85^\circ\text{C}$ )

| Parameter                               | Symbol   | Test Condition                            | Min                 | Typ | Max                 | Unit |
|---|----------|---|---------------------|-----|---------------------|------|
| Differential Input Common Mode Voltage  | $V_{CM}$ | $V_{DD} = 2.5V \pm 5\%$ , $3.3V \pm 10\%$ | 0.05                | —   | —                   | V    |
| Differential Input Swing (peak-to-peak) | $V_{IN}$ |   | 0.2                 | —   | 2.2                 | V    |
| LVC MOS Input High Voltage              | $V_{IH}$ | $V_{DD} = 2.5V \pm 5\%$ , $3.3V \pm 10\%$ | $V_{DD} \times 0.7$ | —   | —                   | V    |
| LVC MOS Input Low Voltage               | $V_{IL}$ | $V_{DD} = 2.5V \pm 5\%$ , $3.3V \pm 10\%$ | —                   | —   | $V_{DD} \times 0.3$ | V    |
| Input Capacitance                       | $C_{IN}$ | CLK0 and CLK1 pins with respect to GND    | —                   | 5   | —                   | pF   |

**Table 3. DC Common Characteristics**(V<sub>DD</sub> = 1.8 V ± 5%, 2.5 V ± 5%, or 3.3 V ± 10%, T<sub>A</sub> = –40 to 85 °C)

| Parameter  | Symbol            | Test Condition   | Min                    | Typ                   | Max                    | Unit |
|--|-------------------|--|------------------------|-----------------------|------------------------|------|
| Supply Current   | I <sub>DD</sub>   |  | —                      | 65                    | 100                    | mA   |
| Output Buffer Supply Current (Per Clock Output) @100 MHz | I <sub>DDOX</sub> | LVPECL (3.3 V)   | —                      | 35                    | —                      | mA   |
|  |                   | Low Power LVPECL (3.3 V)   | —                      | 35                    | —                      | mA   |
|  |                   | LVDS (3.3 V)   | —                      | 20                    | —                      | mA   |
|  |                   | CML (3.3 V)  | —                      | 30                    | —                      | mA   |
|  |                   | HCSL, 100 MHz, 2 pF load (3.3 V)   | —                      | 35                    | —                      | mA   |
|  |                   | CMOS (1.8 V, SFOUT = Open/0), per output, C <sub>L</sub> = 5 pF, 200 MHz | —                      | 5                     | —                      | mA   |
|  |                   | CMOS (2.5 V, SFOUT = Open/0), per output, C <sub>L</sub> = 5 pF, 200 MHz | —                      | 8                     | —                      | mA   |
|  |                   | CMOS (3.3 V, SFOUT = 0/1), per output, C <sub>L</sub> = 5 pF, 200 MHz    | —                      | 15                    | —                      | mA   |
| Voltage Reference  | V <sub>REF</sub>  | V <sub>REF</sub> pin   | —                      | V <sub>DD</sub> /2    | —                      | V    |
| Input High Voltage                                       | V <sub>IH</sub>   | SFOUTx, DIVx, CLK_SEL, OEx   | 0.8 x V <sub>DD</sub>  | —                     | —                      | V    |
| Input Mid Voltage  | V <sub>IM</sub>   | SFOUTx, DIVx<br>3-level input pins                                       | 0.45 x V <sub>DD</sub> | 0.5 x V <sub>DD</sub> | 0.55 x V <sub>DD</sub> | V    |
| Input Low Voltage  | V <sub>IL</sub>   | SFOUTx, DIVx, CLK_SEL, OEx   | —                      | —                     | 0.2 x V <sub>DD</sub>  | V    |
| Internal Pull-down Resistor                              | R <sub>DOWN</sub> | CLK_SEL, DIVx, SFOUTx,   | —                      | 25                    | —                      | kΩ   |
| Internal Pull-up Resistor                                | R <sub>UP</sub>   | OEx, DIVx, SFOUTx  | —                      | 25                    | —                      | kΩ   |

**Table 4. Output Characteristics (LVPECL)**(V<sub>DDOX</sub> = 2.5 V ± 5%, or 3.3 V ± 10%, T<sub>A</sub> = –40 to 85 °C)

| Parameter   | Symbol           | Test Condition | Min                       | Typ  | Max                       | Unit |
|---|------------------|----------------|---------------------------|------|---------------------------|------|
| Output DC Common Mode Voltage   | V <sub>COM</sub> |                | V <sub>DDOX</sub> – 1.595 | —    | V <sub>DDOX</sub> – 1.245 | V    |
| Single-Ended Output Swing   | V <sub>SE</sub>  |                | 0.40                      | 0.80 | 1.050                     | V    |
| <b>*Note:</b> Unused outputs can be left floating. Do not short unused outputs to ground. |                  |                |                           |      |                           |      |

**Table 5. Output Characteristics (Low Power LVPECL)**(V<sub>DDOX</sub> = 2.5 V ± 5%, or 3.3 V ± 10%, T<sub>A</sub> = –40 to 85 °C)

| Parameter                     | Symbol           | Test Condition  | Min                       | Typ  | Max                       | Unit |
|-------------------------------|------------------|---|---------------------------|------|---------------------------|------|
| Output DC Common Mode Voltage | V <sub>COM</sub> | R <sub>L</sub> = 100 Ω across Q <sub>n</sub> and $\overline{Q_n}$ | V <sub>DDOX</sub> – 1.895 |      | V <sub>DDOX</sub> – 1.275 | V    |
| Single-Ended Output Swing     | V <sub>SE</sub>  | R <sub>L</sub> = 100 Ω across Q <sub>n</sub> and $\overline{Q_n}$ | 0.20                      | 0.60 | 0.85                      | V    |

**Table 6. Output Characteristics—CML**(V<sub>DDOX</sub> = 1.8 V ± 5%, 2.5 V ± 5%, or 3.3 V ± 10%, T<sub>A</sub> = –40 to 85 °C)

| Parameter                 | Symbol          | Test Condition                                     | Min | Typ | Max | Unit |
|---------------------------|-----------------|--|-----|-----|-----|------|
| Single-Ended Output Swing | V <sub>SE</sub> | Terminated as shown in Figure 8 (CML termination). | 200 | 400 | 550 | mV   |

**Table 7. Output Characteristics—LVDS**(V<sub>DDOX</sub> = 1.8 V ± 5%, 2.5 V ± 5%, or 3.3 V ± 10%, T<sub>A</sub> = –40 to 85 °C)

| Parameter  | Symbol            | Test Condition  | Min  | Typ  | Max  | Unit |
|--|-------------------|---|------|------|------|------|
| Single-Ended Output Swing  | V <sub>SE</sub>   | R <sub>L</sub> = 100 Ω across Q <sub>N</sub> and $\overline{Q_N}$   | 200  | —    | 490  | mV   |
| Output Common Mode Voltage<br>(V <sub>DDO</sub> = 2.5 V or 3.3V) | V <sub>COM1</sub> | V <sub>DDOX</sub> = 2.38 to 2.63 V, 2.97 to 3.63 V, R <sub>L</sub> = 100 Ω across Q <sub>N</sub> and $\overline{Q_N}$ | 1.10 | 1.25 | 1.35 | V    |
| Output Common Mode Voltage<br>(V <sub>DDO</sub> = 1.8 V)         | V <sub>COM2</sub> | V <sub>DDOX</sub> = 1.71 to 1.89 V, R <sub>L</sub> = 100 Ω across Q <sub>N</sub> and $\overline{Q_N}$                 | 0.85 | 0.97 | 1.25 | V    |

**Table 8. Output Characteristics—LVCMOS**(V<sub>DDOX</sub> = 1.8 V ± 5%, 2.5 V ± 5%, or 3.3 V ± 10%, T<sub>A</sub> = –40 to 85 °C)

| Parameter           | Symbol          | Test Condition | Min                      | Typ | Max                      | Unit |
|---------------------|-----------------|----------------|--------------------------|-----|--------------------------|------|
| Output Voltage High | V <sub>OH</sub> |                | 0.75 x V <sub>DDOX</sub> | —   | —                        | V    |
| Output Voltage Low  | V <sub>OL</sub> |                | —                        | —   | 0.25 x V <sub>DDOX</sub> | V    |

**\*Note:** I<sub>OH</sub> and I<sub>OL</sub> per the Output Signal Format Table for specific V<sub>DDOX</sub> and SFOUTx settings.

**Table 9. Output Characteristics—HCSL**(V<sub>DDOX</sub> = 3.3 V ± 10%, T<sub>A</sub> = –40 to 85 °C)

| Parameter                 | Symbol          | Test Condition               | Min  | Typ | Max | Unit |
|---------------------------|-----------------|------------------------------|------|-----|-----|------|
| Output Voltage High       | V <sub>OH</sub> | R <sub>L</sub> = 50 Ω to GND | 550  | 700 | 900 | mV   |
| Output Voltage Low        | V <sub>OL</sub> | R <sub>L</sub> = 50 Ω to GND | –150 | 0   | 150 | mV   |
| Single-Ended Output Swing | V <sub>SE</sub> | R <sub>L</sub> = 50 Ω to GND | 450  | 700 | 850 | mV   |
| Crossing Voltage          | V <sub>C</sub>  | R <sub>L</sub> = 50 Ω to GND | 250  | 350 | 550 | mV   |

**Table 10. AC Characteristics**(V<sub>DD</sub> = V<sub>DDOX</sub> = 1.8 V ± 5%, 2.5 V ± 5%, or 3.3 V ± 10%, T<sub>A</sub> = –40 to 85 °C)

| Parameter                                  | Symbol                         | Test Condition   | Min  | Typ | Max  | Unit |
|--|--------------------------------|--|------|-----|------|------|
| Frequency                                  | F                              | LVPECL, low power LVPECL, LVDS, CML, HCSL  | dc   | —   | 1250 | GHz  |
|  |                                | LVC MOS  | dc   | —   | 200  | MHz  |
| Duty Cycle <sup>6</sup>                    | D <sub>C</sub>                 | 200 MHz, 20/80% T <sub>R</sub> /T <sub>F</sub> < 10% of period (LVC MOS) (12 mA drive) | 40   | 50  | 60   | %    |
|  |                                | 20/80% T <sub>R</sub> /T <sub>F</sub> < 10% of period (Differential)                   | 47   | 50  | 53   | %    |
| Minimum Input Clock Slew Rate <sup>5</sup> | SR                             | Required to meet prop delay and additive jitter specifications (20–80%)                | 0.75 | —   | —    | V/ns |
| Output Rise/Fall Time                      | T <sub>R</sub> /T <sub>F</sub> | LVDS, 20/80%   | —    | —   | 325  | ps   |
|  |                                | LVPECL, 20/80%   | —    | —   | 350  | ps   |
|  |                                | HCSL <sup>1</sup> , 20/80%   | —    | —   | 280  | ps   |
|  |                                | CML, 20/80%  | —    | —   | 350  | ps   |
|  |                                | Low-Power LVPECL, 20/80%   | —    | —   | 325  | ps   |
|  |                                | LVC MOS 200 MHz, 20/80%, 2 pF load   | —    | —   | 750  | ps   |

**Notes:**

1. HCSL measurements were made with receiver termination. See Figure 8 on page 17.
2. Output to Output skew specified for outputs with an identical configuration.
3. Defined as skew between any output on different devices operating at the same supply voltage, temperature, and equal load condition. Using the same type of inputs on each device, the outputs are measured at the differential cross points.
4. Measured for 156.25 MHz carrier frequency. Sine-wave noise added to V<sub>DDOX</sub> (3.3 V = 100 mV<sub>PP</sub>) and noise spur amplitude measured. See “AN491: Power Supply Rejection for Low-Jitter Clocks” for further details.
5. When using the on-chip clock divider, a minimum input clock slew rate of 30 mV/ns is required.
6. 50% input duty cycle.

**Table 10. AC Characteristics (Continued)**(V<sub>DD</sub> = V<sub>DDOX</sub> = 1.8 V ± 5%, 2.5 V ± 5%, or 3.3 V ± 10%, T<sub>A</sub> = -40 to 85 °C)

| Parameter                                 | Symbol                                 | Test Condition                    | Min  | Typ  | Max  | Unit |
|---|--|-----------------------------------|------|------|------|------|
| Minimum Input Pulse Width                 | T <sub>W</sub>                         |                                   | 360  | —    | —    | ps   |
| Propagation Delay                         | T <sub>PLH</sub> ,<br>T <sub>PHL</sub> | LVC MOS (12mA drive with no load) | 1250 | 2000 | 2750 | ps   |
|   |  | LVPECL                            | 600  | 800  | 1000 | ps   |
|   |  | LVDS                              | 600  | 800  | 1000 | ps   |
| Output Enable Time                        | T <sub>EN</sub>                        | F = 1 MHz                         | —    | 2500 | —    | ns   |
|   |  | F = 100 MHz                       | —    | 30   | —    | ns   |
|   |  | F = 725 MHz                       | —    | 5    | —    | ns   |
| Output Disable Time                       | T <sub>DIS</sub>                       | F = 1 MHz                         | —    | 2000 | —    | ns   |
|   |  | F = 100 MHz                       | —    | 30   | —    | ns   |
|   |  | F = 725 MHz                       | —    | 5    | —    | ns   |
| Output to Output Skew <sup>2</sup>        | T <sub>SK</sub>                        | LVC MOS (12 mA drive to no load)  | —    | 50   | 120  | ps   |
|   |  | LVPECL                            | —    | 35   | 70   | ps   |
|   |  | LVDS                              | —    | 35   | 70   | ps   |
| Part to Part Skew <sup>3</sup>            | T <sub>PS</sub>                        | Differential                      | —    | —    | 150  | ps   |
| Power Supply Noise Rejection <sup>4</sup> | PSRR                                   | 10 kHz sinusoidal noise           | —    | -63  | —    | dBc  |
|   |  | 100 kHz sinusoidal noise          | —    | -62  | —    | dBc  |
|   |  | 500 kHz sinusoidal noise          | —    | -58  | —    | dBc  |
|   |  | 1 MHz sinusoidal noise            | —    | -55  | —    | dBc  |

**Notes:**

1. HCSL measurements were made with receiver termination. See Figure 8 on page 17.
2. Output to Output skew specified for outputs with an identical configuration.
3. Defined as skew between any output on different devices operating at the same supply voltage, temperature, and equal load condition. Using the same type of inputs on each device, the outputs are measured at the differential cross points.
4. Measured for 156.25 MHz carrier frequency. Sine-wave noise added to V<sub>DDOX</sub> (3.3 V = 100 mV<sub>PP</sub>) and noise spur amplitude measured. See "AN491: Power Supply Rejection for Low-Jitter Clocks" for further details.
5. When using the on-chip clock divider, a minimum input clock slew rate of 30 mV/ns is required.
6. 50% input duty cycle.

Table 11. Additive Jitter, Differential Clock Input

| $V_{DD}$ | Input <sup>1,2</sup> |              |  |   | Output       | Additive Jitter<br>(fs rms, 12 kHz to 20 MHz) <sup>3</sup> |     |
|----------|----------------------|--------------|--|---|--------------|--|-----|
|          | Freq<br>(MHz)        | Clock Format | Amplitude<br>$V_{IN}$<br>(Single-Ended,<br>Peak-to-Peak) | Differential<br>20%-80% Slew<br>Rate (V/ns) | Clock Format | Typ  | Max |
| 3.3      | 725                  | Differential | 0.15   | 0.637                                       | LVPECL       | 45   | 65  |
| 3.3      | 725                  | Differential | 0.15   | 0.637                                       | LVDS         | 50   | 65  |
| 3.3      | 156.25               | Differential | 0.5  | 0.458                                       | LVPECL       | 160  | 185 |
| 3.3      | 156.25               | Differential | 0.5  | 0.458                                       | LVDS         | 150  | 200 |
| 2.5      | 725                  | Differential | 0.15   | 0.637                                       | LVPECL       | 45   | 65  |
| 2.5      | 725                  | Differential | 0.15   | 0.637                                       | LVDS         | 50   | 65  |
| 2.5      | 156.25               | Differential | 0.5  | 0.458                                       | LVPECL       | 145  | 185 |
| 2.5      | 156.25               | Differential | 0.5  | 0.458                                       | LVDS         | 145  | 195 |

**Notes:**

1. For best additive jitter results, use the fastest slew rate possible. See “AN766: Understanding and Optimizing Clock Buffer’s Additive Jitter Performance” for more information.
2. AC-coupled differential inputs.
3. Measured differentially using a balun at the phase noise analyzer input. See Figure 1.

Table 12. Additive Jitter, Single-Ended Clock Input

| $V_{DD}$ | Input <sup>1,2</sup> |              |  |                                   | Output               | Additive Jitter<br>(fs rms, 12 kHz to 20 MHz) <sup>3</sup> |     |
|----------|----------------------|--------------|--|-----------------------------------|----------------------|--|-----|
|          | Freq<br>(MHz)        | Clock Format | Amplitude<br>$V_{IN}$<br>(single-ended,<br>peak to peak) | SE 20%-80%<br>Slew Rate<br>(V/ns) | Clock Format         | Typ  | Max |
| 3.3      | 200                  | Single-ended | 1.70   | 1                                 | LVC MOS <sup>4</sup> | 120  | 160 |
| 3.3      | 156.25               | Single-ended | 2.18   | 1                                 | LVPECL               | 160  | 185 |
| 3.3      | 156.25               | Single-ended | 2.18   | 1                                 | LVDS                 | 150  | 200 |
| 3.3      | 156.25               | Single-ended | 2.18   | 1                                 | LVC MOS <sup>4</sup> | 130  | 180 |
| 2.5      | 200                  | Single-ended | 1.70   | 1                                 | LVC MOS <sup>5</sup> | 120  | 160 |
| 2.5      | 156.25               | Single-ended | 2.18   | 1                                 | LVPECL               | 145  | 185 |
| 2.5      | 156.25               | Single-ended | 2.18   | 1                                 | LVDS                 | 145  | 195 |
| 2.5      | 156.25               | Single-ended | 2.18   | 1                                 | LVC MOS <sup>5</sup> | 140  | 180 |

**Notes:**

1. For best additive jitter results, use the fastest slew rate possible. See “AN766: Understanding and Optimizing Clock Buffer’s Additive Jitter Performance” for more information.
2. DC-coupled single-ended inputs.
3. Measured differentially using a balun at the phase noise analyzer input. See Figure 1.
4. Drive Strength: 12 mA, 3.3 V (SFOUT = 11). LVC MOS jitter is measured single-ended.
5. Drive Strength: 9 mA, 2.5 V (SFOUT = 11). LVC MOS jitter is measured single-ended.

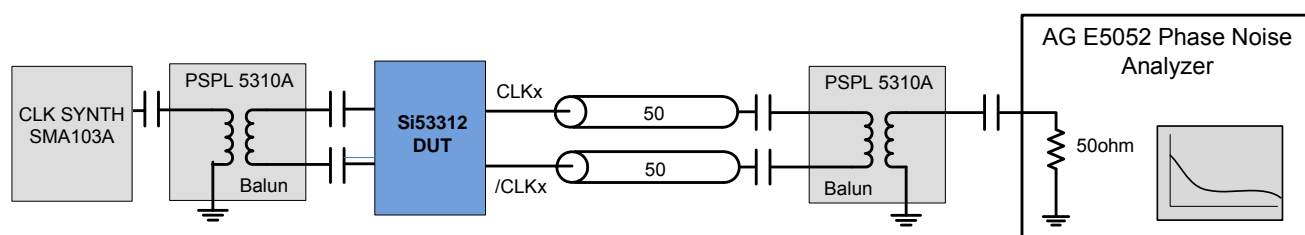


Figure 1. Differential Measurement Method Using a Balun



**Table 13. Thermal Conditions**

| Parameter                               | Symbol        | Test Condition | Value | Unit |
|---|---------------|----------------|-------|------|
| Thermal Resistance, Junction to Ambient | $\theta_{JA}$ | Still air      | 49.6  | °C/W |
| Thermal Resistance, Junction to Case    | $\theta_{JC}$ | Still air      | 32.3  | °C/W |

**Table 14. Absolute Maximum Ratings**

| Parameter   | Symbol     | Test Condition                                     | Min  | Typ | Max            | Unit |
|---|------------|--|------|-----|----------------|------|
| Storage Temperature   | $T_S$      |  | -55  | —   | 150            | °C   |
| Supply Voltage  | $V_{DD}$   |  | -0.5 | —   | 3.8            | V    |
| Input Voltage   | $V_{IN}$   |  | -0.5 | —   | $V_{DD} + 0.3$ | V    |
| Output Voltage  | $V_{OUT}$  |  | —    | —   | $V_{DD} + 0.3$ | V    |
| ESD Sensitivity   | HBM        | HBM, 100 pF, 1.5 k $\Omega$                        | —    | —   | 2000           | V    |
| ESD Sensitivity   | CDM        |  | —    | —   | 500            | V    |
| Peak Soldering Reflow Temperature   | $T_{PEAK}$ | Pb-Free; Solder reflow profile per JEDEC J-STD-020 | —    | —   | 260            | °C   |
| Maximum Junction Temperature  | $T_J$      |  | —    | —   | 125            | °C   |
| <b>Note:</b> Stresses beyond those listed in this table may cause permanent damage to the device. Functional operation specification compliance is not implied at these conditions. Exposure to maximum rating conditions for extended periods may affect device reliability. |            |  |      |     |                |      |

## 2. Functional Description

The Si53312 is a low jitter, low skew 1:10 differential buffer with an integrated 2:1 input mux. The device has a universal input that accepts most common differential or LVCMOS input signals. A clock select pin is used to select the active input clock. The selected clock input is routed to two independent banks of outputs. Each output bank features control pins to select signal format, output enable, output divider setting and LVCMOS drive strength.

### 2.1. Universal, Any-Format Input

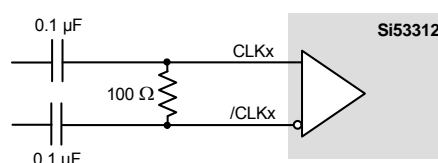
The Si53312 has a universal input stage that enables simple interfacing to a wide variety of clock formats, including LVPECL, LVCMOS, LVDS, HCSL, and CML. Tables 15 and 16 summarize the various input ac- and dc-coupling options supported by the device. Figures 3 and 4 show the recommended input clock termination options.

**Table 15. LVPECL, LVCMOS, and LVDS**

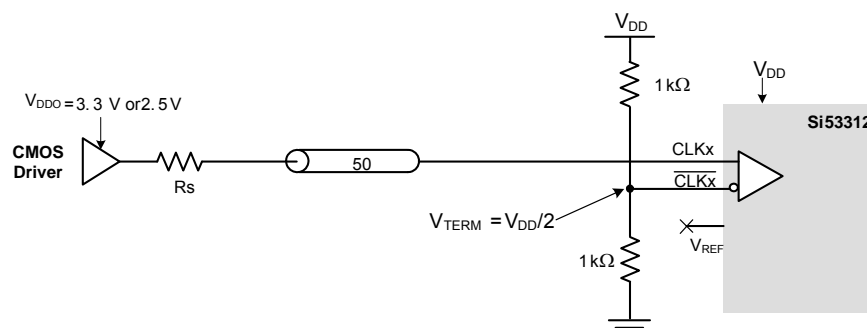
|           | LVPECL    |           | LVCMOS    |           | LVDS      |           |
|-----------|-----------|-----------|-----------|-----------|-----------|-----------|
|           | AC-Couple | DC-Couple | AC-Couple | DC-Couple | AC-Couple | DC-Couple |
| 1.8 V     | N/A       | N/A       | No        | No        | Yes       | No        |
| 2.5/3.3 V | Yes       | Yes       | No        | Yes       | Yes       | Yes       |

**Table 16. HCSL and CML**

|           | HCSL      |             | CML       |           |
|-----------|-----------|-------------|-----------|-----------|
|           | AC-Couple | DC-Couple   | AC-Couple | DC-Couple |
| 1.8 V     | No        | No          | Yes       | No        |
| 2.5/3.3 V | Yes       | Yes (3.3 V) | Yes       | No        |

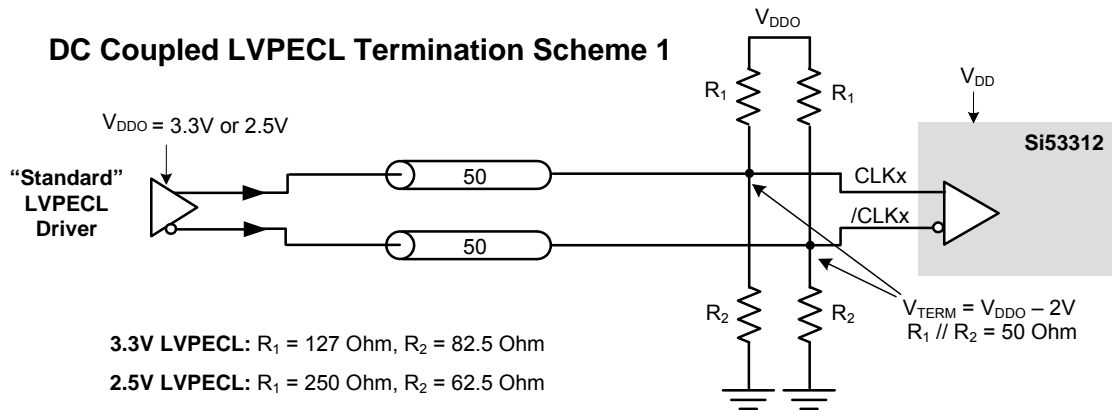


**Figure 2. Differential LVPECL, LVDS, CML AC-Coupled Input Termination**

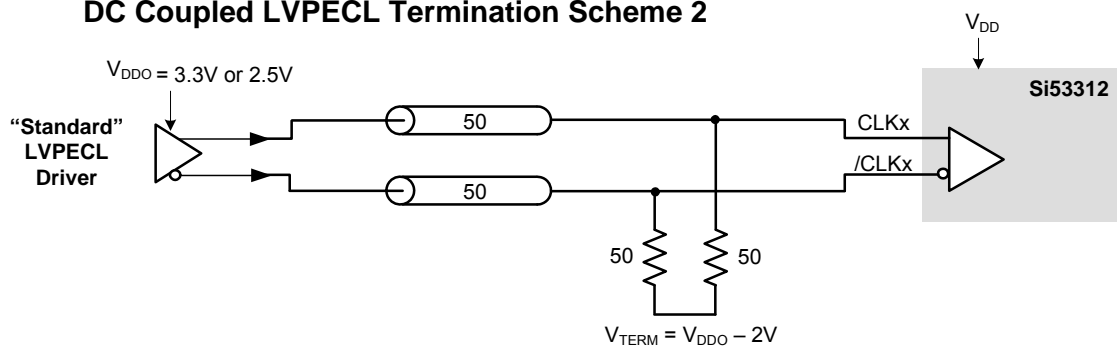


**Figure 3. LVCMOS DC-Coupled Input Termination**

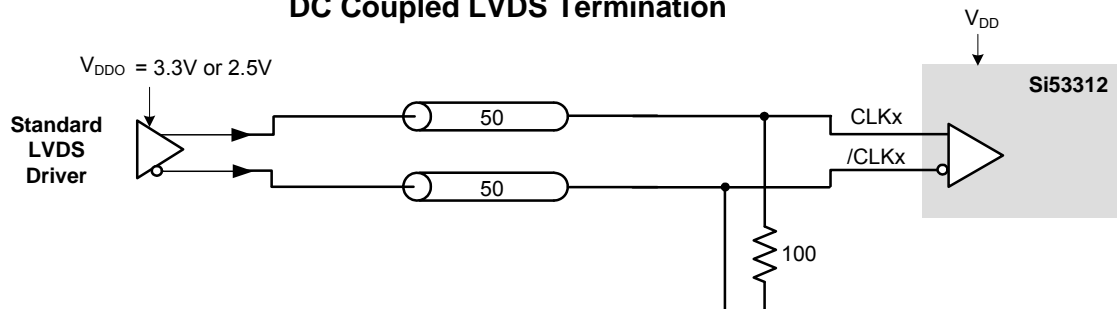
## DC Coupled LVPECL Termination Scheme 1



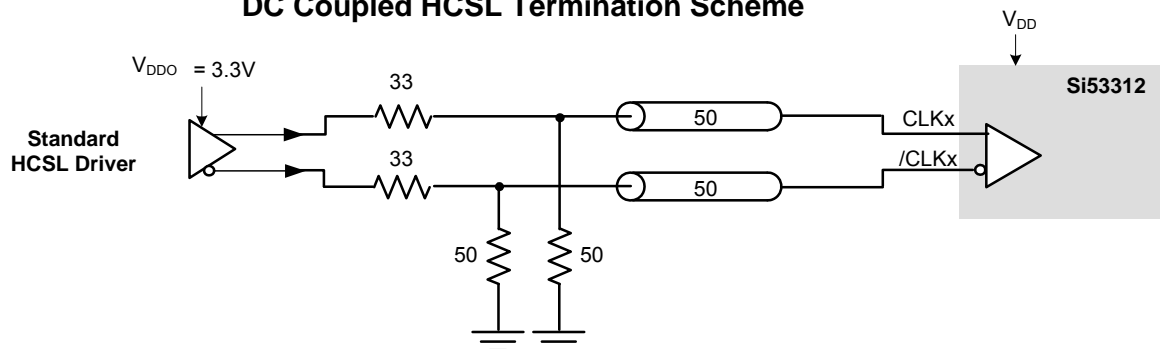
## DC Coupled LVPECL Termination Scheme 2



## DC Coupled LVDS Termination



## DC Coupled HCSL Termination Scheme

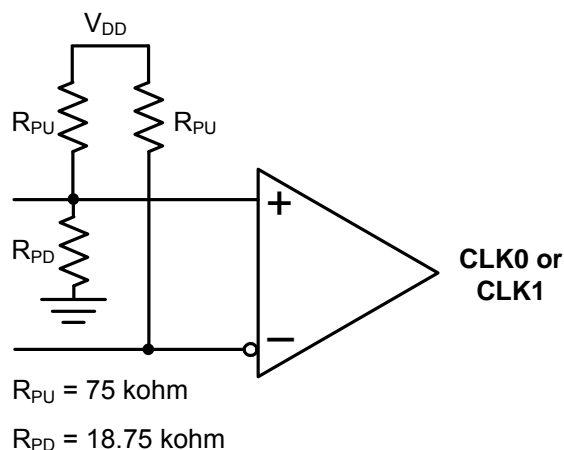


Note: 33 Ohm series termination is optional depending on the location of the receiver.

**Figure 4. Differential DC-Coupled Input Terminations**

## 2.2. Input Bias Resistors

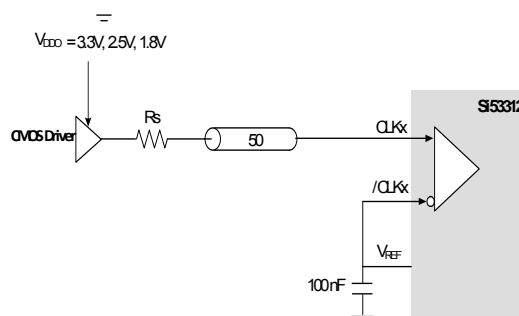
Internal bias resistors ensure a differential output low condition in the event that the clock inputs are not connected. The noninverting input is biased with a 18.75 k $\Omega$  pulldown to GND and a 75 k $\Omega$  pullup to V<sub>DD</sub>. The inverting input is biased with a 75 k $\Omega$  pullup to V<sub>DD</sub>.



**Figure 5. Input Bias Resistors**

## 2.3. Voltage Reference (V<sub>REF</sub>)

The V<sub>REF</sub> pin can be used to bias the input receiver, as shown in Figure 6 when a single-ended input clock (such as LVCMOS) is used. Note that V<sub>REF</sub> = V<sub>DD</sub>/2 and should be compatible with the VCM rating of the single-ended input clock driving the CLK0 or CLK1 inputs. To optimize jitter and duty cycle performance, use the circuit in Figure 3. V<sub>REF</sub> pin should be left floating when differential clocks are used.



**Figure 6. Using Voltage Reference with Single-Ended Input Clock**

## 2.4. Universal, Any-Format Output Buffer

The highly flexible output drivers support a wide range of clock signal formats, including LVPECL, low power LVPECL, LVDS, CML, HCSL, and LVCMOS. SFOUTx[1] and SFOUTx[0] are 3-level inputs that can be pinstrapped to select the Bank A and Bank B clock signal formats independently. This feature enables the device to be used for format/level translation in addition to clock distribution, minimizing the number of unique buffer part numbers required in a typical application and simplifying design reuse. For EMI reduction applications, four LVCMOS drive strength options are available for each  $V_{DDO}$  setting.

**Table 17. Output Signal Format Selection**

| SFOUTx[1]   | SFOUTx[0] | $V_{DDOX} = 3.3\text{ V}$ | $V_{DDOX} = 2.5\text{ V}$ | $V_{DDOX} = 1.8\text{ V}$ |
|---|-----------|---------------------------|---------------------------|---------------------------|
| Open*   | Open*     | LVPECL                    | LVPECL                    | N/A                       |
| 0   | 0         | LVDS                      | LVDS                      | LVDS                      |
| 0   | 1         | LVCMOS, 24 mA drive       | LVCMOS, 18 mA drive       | LVCMOS, 12 mA drive       |
| 1   | 0         | LVCMOS, 18 mA drive       | LVCMOS, 12 mA drive       | LVCMOS, 9 mA drive        |
| 1   | 1         | LVCMOS, 12 mA drive       | LVCMOS, 9 mA drive        | LVCMOS, 6 mA drive        |
| Open*   | 0         | LVCMOS, 6 mA drive        | LVCMOS, 4 mA drive        | LVCMOS, 2 mA drive        |
| Open*   | 1         | LVPECL Low power          | LVPECL Low power          | N/A                       |
| 0   | Open*     | CML                       | CML                       | CML                       |
| 1   | Open*     | HCSL                      | HCSL                      | HCSL                      |
| <b>*Note:</b> SFOUTx[1:0] are 3-level input pins. Tie low for “0” setting. Tie high for “1” setting. When left open, the pin is internally biased to $V_{DD}/2$ . |           |                           |                           |                           |

## 2.5. Input Mux and Output Enable Logic

The Si53312 provides two clock inputs for applications that need to select between one of two clock sources. The CLK\_SEL pin selects the active clock input. The table below summarizes the input and output clock based on the input mux and output enable pin settings.

**Table 18. Input Mux and Output Enable Logic**

| CLK_SEL   | CLK0 | CLK1 | OE <sup>1</sup> | Q <sup>2</sup> |
|---|------|------|-----------------|----------------|
| L   | L    | X    | H               | L              |
| L   | H    | X    | H               | H              |
| H   | X    | L    | H               | L              |
| H   | X    | H    | H               | H              |
| X   | X    | X    | L               | L <sup>3</sup> |
| <b>Notes:</b> <ol style="list-style-type: none"> <li>1. Output enable active high</li> <li>2. On the next negative transition of CLK0 or CLK1.</li> <li>3. Single-end: Q=low, <math>\overline{Q}</math>=high<br/>Differential: Q=low, <math>\overline{Q}</math>=high</li> </ol> |      |      |                 |                |

## 2.6. Flexible Output Divider

The Si53312 provides optional clock division in addition to clock distribution. The divider setting for each bank of output clocks is selected via 3-level control pins as shown in the table below. Leaving the DIVx pins open will force a divider value of 1, which is the default mode of operation. Note that when using the on-chip clock divider, a minimum input clock slew rate of 30 mV/ns is required.

**Table 19. Divider Selection**

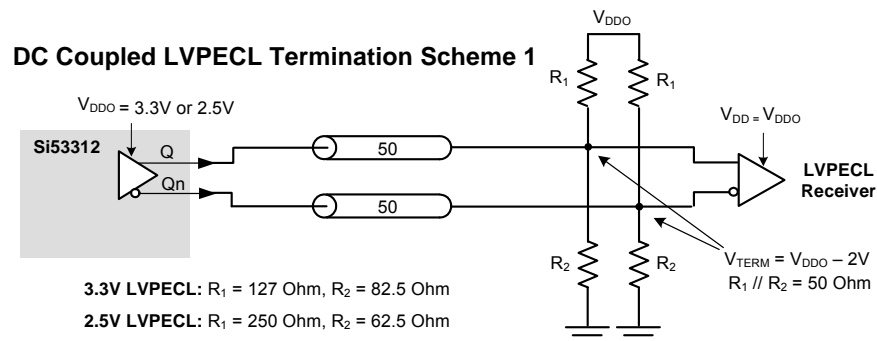
| DIVx <sup>1</sup>  | Divider Value |
|--|---------------|
| Open <sup>2</sup>  | ÷1 (default)  |
| 0 <sup>3</sup>   | ÷2            |
| 1 <sup>3</sup>   | ÷4            |
| <b>Notes:</b> <ol style="list-style-type: none"> <li>1. DIVx are 3-level input pins. Tie low for “0” setting. Tie high for “1” setting. When left open, the pin is internally biased to <math>V_{DD}/2</math>.</li> <li>2. For frequency range dc to 1.25 GHz.</li> <li>3. For frequency range dc to 725 MHz.</li> </ol> |               |

## 2.7. Power Supply ( $V_{DD}$ and $V_{DDOX}$ )

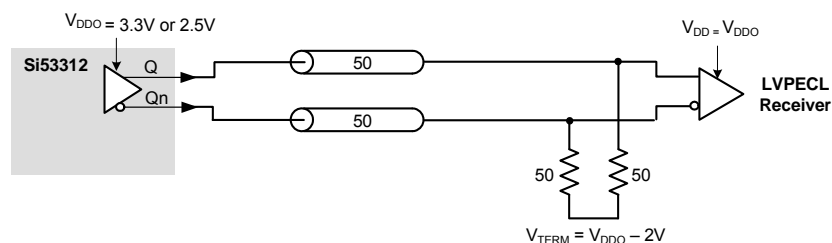
The device includes separate core ( $V_{DD}$ ) and output driver supplies ( $V_{DDOX}$ ). This feature allows the core to operate at a lower voltage than  $V_{DDOX}$ , reducing current consumption in mixed supply applications. The core  $V_{DD}$  supports 3.3, 2.5, or 1.8 V. Each output bank has its own  $V_{DDOX}$  supply, supporting 3.3, 2.5, or 1.8 V as defined in Table 1.

## 2.8. Output Clock Termination Options

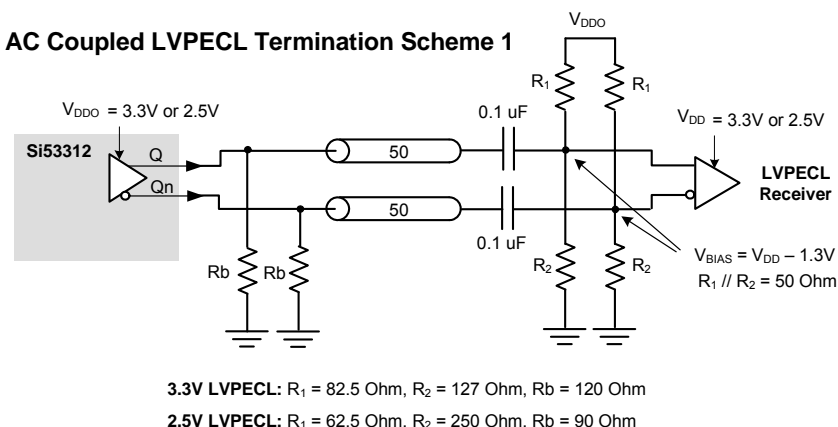
The recommended output clock termination options are shown below.



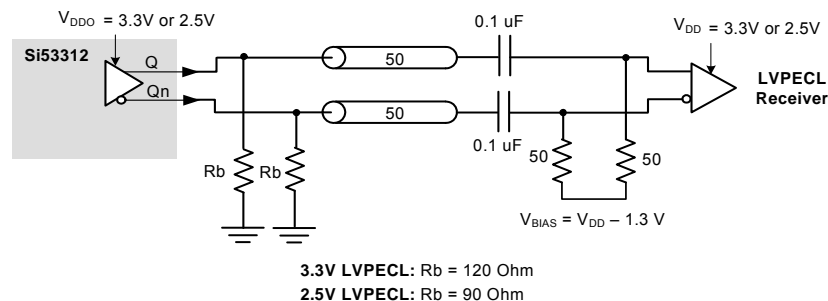
### DC Coupled LVPECL Termination Scheme 2



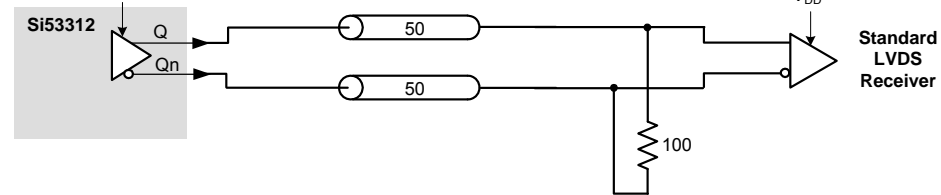
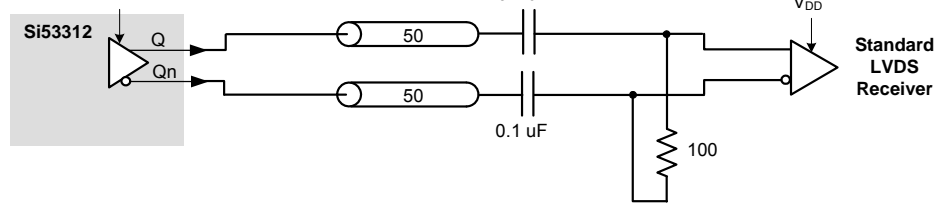
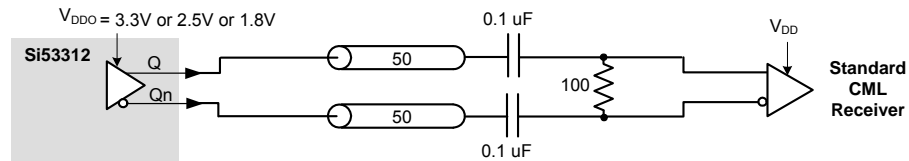
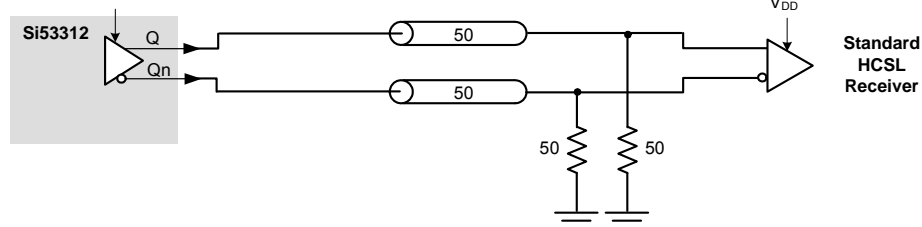
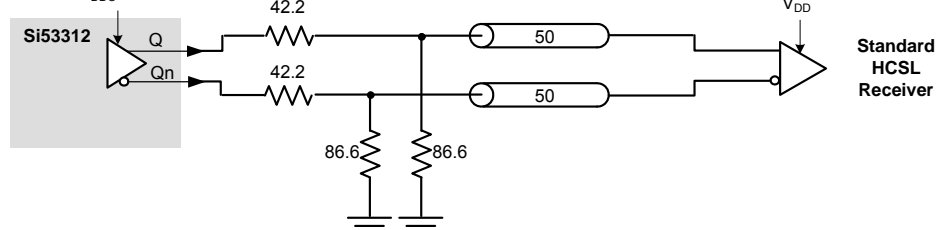
### AC Coupled LVPECL Termination Scheme 1



### AC Coupled LVPECL Termination Scheme 2



**Figure 7. LVPECL Output Termination**

**DC Coupled LVDS and Low-Power LVPECL Termination** $V_{DDO} = 3.3\text{ V or }2.5\text{ V, or }1.8\text{ V (LVDS only)}$ **AC Coupled LVDS and Low-Power LVPECL Termination** $V_{DDO} = 3.3\text{ V or }2.5\text{ V or }1.8\text{ V (LVDS only)}$ **AC Coupled CML Termination** $V_{DDO} = 3.3\text{ V or }2.5\text{ V or }1.8\text{ V}$ **DC Coupled HCSL Receiver Termination** $V_{DDO} = 3.3\text{ V}$ **DC Coupled HCSL Source Termination** $V_{DDO} = 3.3\text{ V}$ **Figure 8. LVDS, CML, HCSL, and Low-Power LVPECL Output Termination**



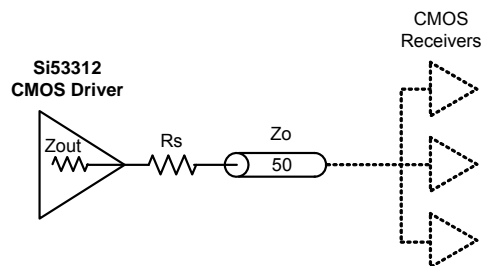


Figure 9. LVC MOS Output Termination

Table 20. Recommended LVC MOS  $R_s$  Series Termination

| SFOUTx[1] | SFOUTx[0] | $R_s$ (ohms) |       |       |
|-----------|-----------|--------------|-------|-------|
|           |           | 3.3 V        | 2.5 V | 1.8 V |
| 0         | 1         | 33           | 33    | 33    |
| 1         | 0         | 33           | 33    | 33    |
| 1         | 1         | 33           | 33    | 0     |
| Open      | 0         | 0            | 0     | 0     |

2.8.1. LVC MOS Output Termination To Support 1.5 V and 1.2 V

LVC MOS clock outputs are natively supported at 1.8 V, 2.5 V, and 3.3 V. However, 1.2 V and 1.5 V LVC MOS clock outputs can be supported via a simple resistor divider network that will translate the buffer's 1.8 V output to a lower voltage as shown in Figure 10.

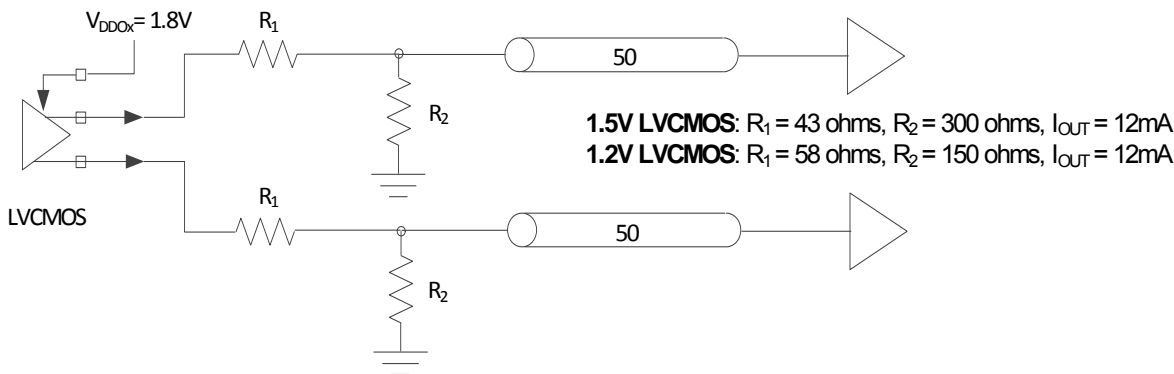


Figure 10. 1.5V and 1.2V LVC MOS Low-Voltage Output Termination

## 2.9. AC Timing Waveforms

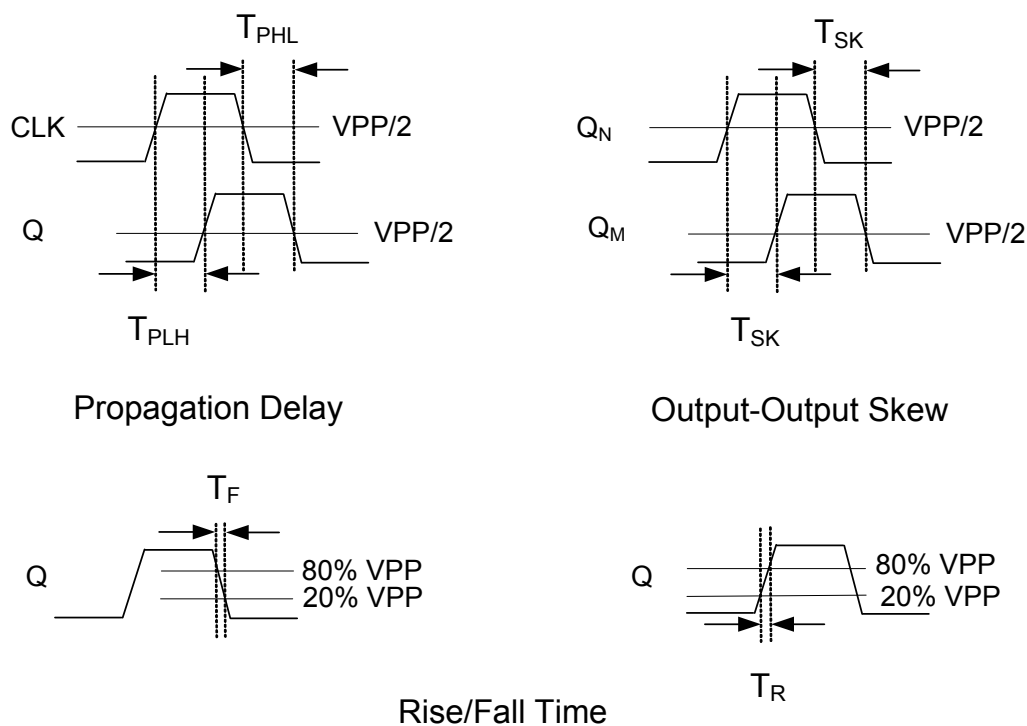
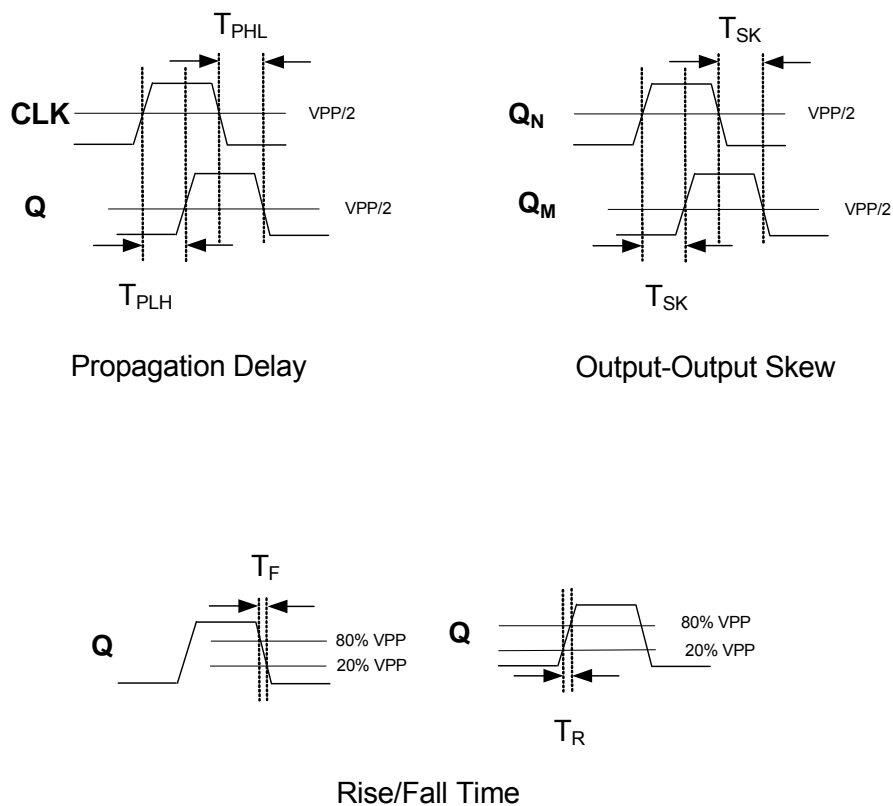


Figure 11. AC Waveforms

## 2.10. AC Timing Waveforms



**Figure 12. AC Waveforms**

## 2.11. Typical Phase Noise Performance

Each of the following three figures shows three phase noise plots superimposed on the same diagram.

**Source Jitter:** Reference clock phase noise.

**Total Jitter (SE):** Combined source and clock buffer phase noise measured as a single-ended output to the phase noise analyzer and integrated from 12 kHz to 20 MHz.

**Total Jitter (Diff):** Combined source and clock buffer phase noise measured as a differential output to the phase noise analyzer and integrated from 12 kHz to 20 MHz. The differential measurement as shown in each figure is made using a balun. See Figure 1 on page 9.

**Note:** To calculate the total RMS phase jitter when adding a buffer to your clock tree, use the root-sum-square (RSS).

The total jitter is a measure of the source plus the buffer's additive phase jitter. The additive jitter (rms) of the buffer can then be calculated (via root-sum-square addition).

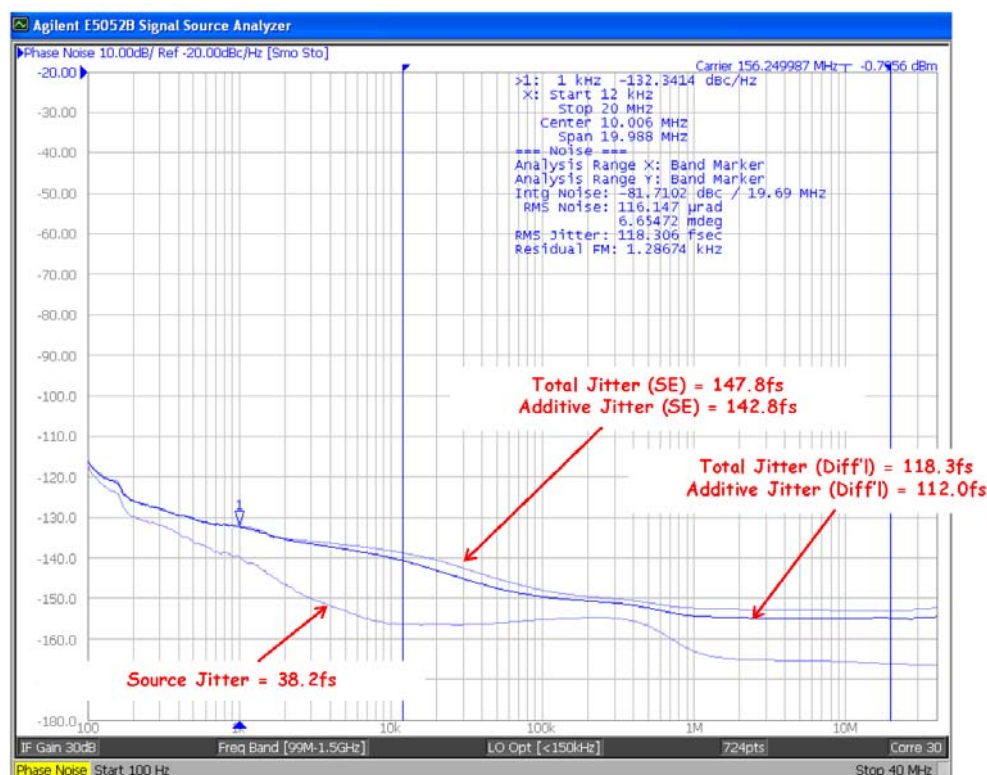


Figure 13. Source Jitter (156.25 MHz)

Table 21. Source Jitter (156.25 MHz)

| Frequency (MHz) | Diff'l Input Slew Rate (V/ns) | Source Jitter (fs) | Total Jitter (SE) (fs) | Additive Jitter (SE) (fs) | Total Jitter (Diff'l) (fs) | Additive Jitter (Diff'l) (fs) |
|-----------------|-------------------------------|--------------------|------------------------|---------------------------|----------------------------|-------------------------------|
| 156.25          | 1.0                           | 38.2               | 147.8                  | 142.8                     | 118.3                      | 112.0                         |

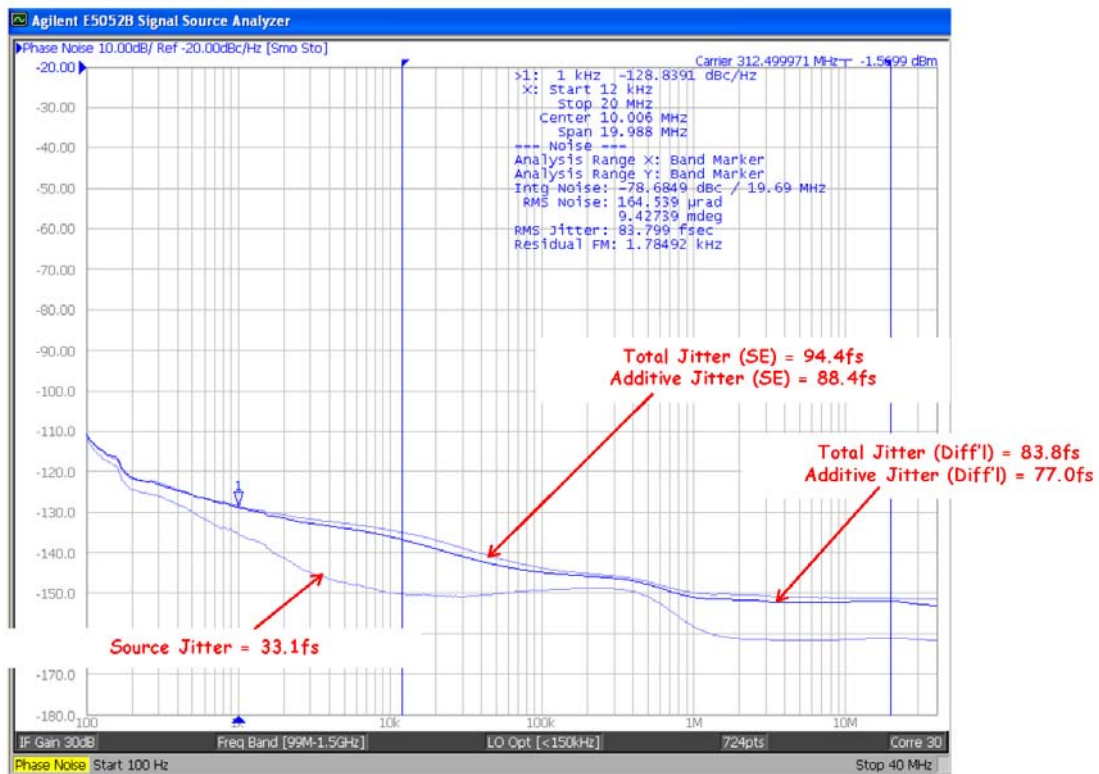


Figure 14. Single-ended Total Jitter (312.5 MHz)

Table 22. Single-ended Total Jitter (312.5 MHz)

| Frequency (MHz) | Diff'l Input Slew Rate (V/ns) | Source Jitter (fs) | Total Jitter (SE) (fs) | Additive Jitter (SE) (fs) | Total Jitter (Diff'l) (fs) | Additive Jitter (Diff'l) (fs) |
|-----------------|-------------------------------|--------------------|------------------------|---------------------------|----------------------------|-------------------------------|
| 312.5           | 1.0                           | 33.10              | 94.39                  | 88.39                     | 83.80                      | 76.99                         |

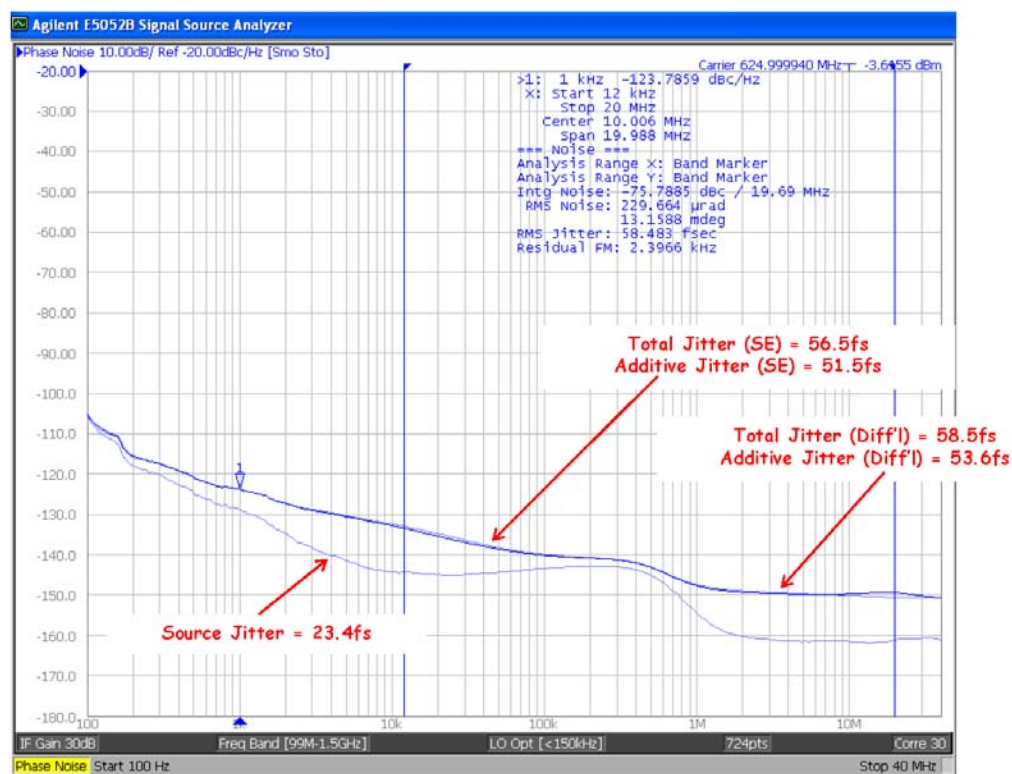


Figure 15. Differential Total Jitter (625 MHz)

Table 23. Differential Total Jitter (625 MHz)

| Frequency (MHz) | Diff'l Input Slew Rate (V/ns) | Source Jitter (fs) | Total Jitter (SE) (fs) | Additive Jitter (SE) (fs) | Total Jitter (Diff'l) (fs) | Additive Jitter (Diff'l) (fs) |
|-----------------|-------------------------------|--------------------|------------------------|---------------------------|----------------------------|-------------------------------|
| 625             | 1.0                           | 23.4               | 56.5                   | 51.5                      | 58.5                       | 53.6                          |

## 2.12. Input Mux Noise Isolation

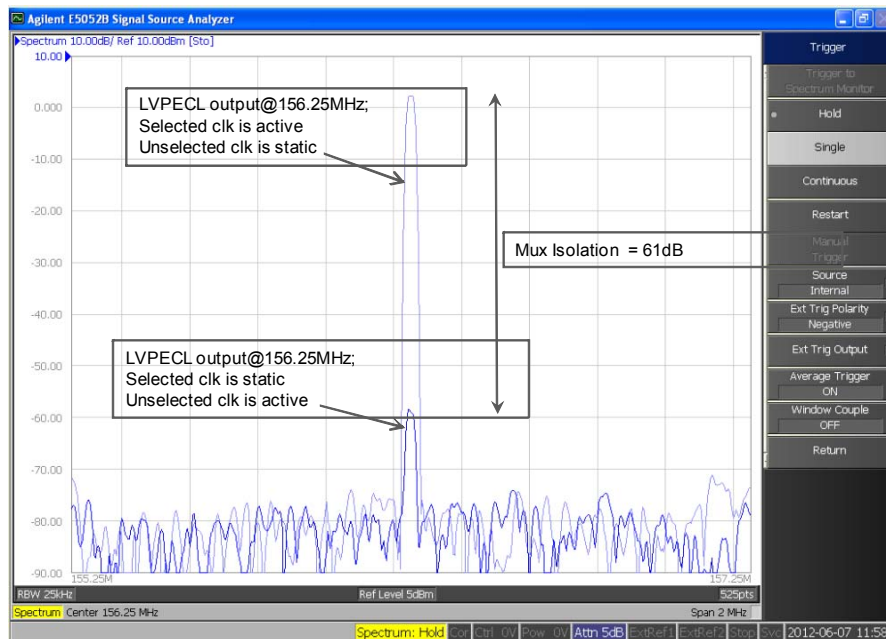
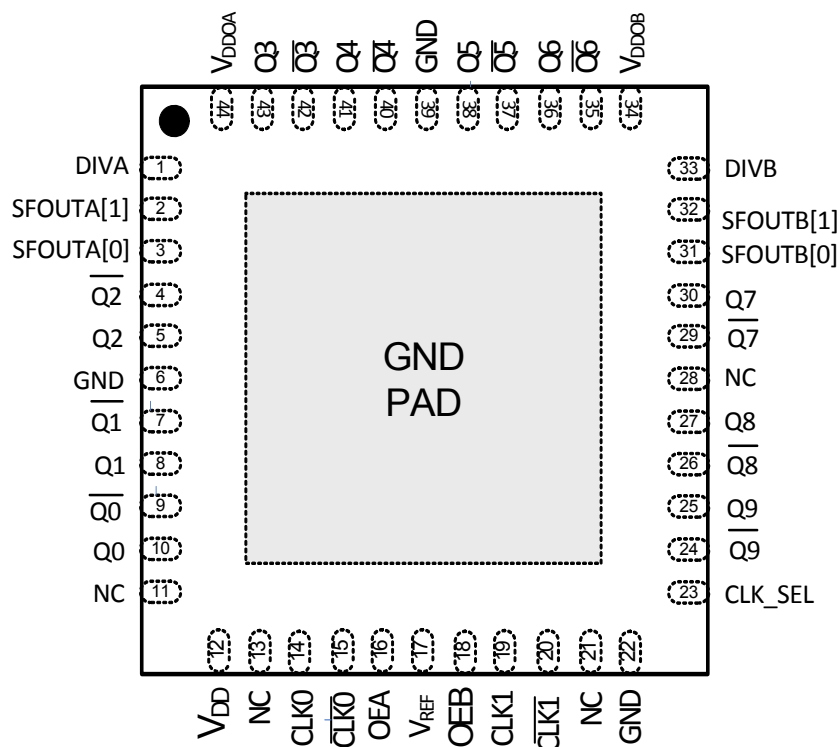


Figure 16. Input Mux Noise Isolation

## 2.13. Power Supply Noise Rejection

The device supports on-chip supply voltage regulation to reject noise present on the power supply, simplifying low jitter operation in real-world environments. This feature enables robust operation alongside FPGAs, ASICs and SoCs and may reduce board-level filtering requirements. For more information, see AN491: “Power Supply Rejection for Low Jitter Clocks”.

### 3. Pin Description: 44-Pin QFN



**Table 24. Si53312 44-Pin QFN Descriptions**

| Pin # | Name            | Description   |
|-------|-----------------|---|
| 1     | DIVA            | Output divider control pin for Bank A.<br>Three-level input control. Internally biased at $V_{DD}/2$ . Can be left floating or tied to ground or $V_{DD}$ .       |
| 2     | SFOUTA[1]       | Output signal format control pin for Bank A.<br>Three-level input control. Internally biased at $V_{DD}/2$ . Can be left floating or tied to ground or $V_{DD}$ . |
| 3     | SFOUTA[0]       | Output signal format control pin for Bank A.<br>Three-level input control. Internally biased at $V_{DD}/2$ . Can be left floating or tied to ground or $V_{DD}$ . |
| 4     | $\overline{Q2}$ | Output clock 2 (complement).  |
| 5     | Q2              | Output clock 2.   |
| 6     | GND             | Ground.   |
| 7     | $\overline{Q1}$ | Output clock 1 (complement).  |
| 8     | Q1              | Output clock 1.   |



Table 24. Si53312 44-Pin QFN Descriptions (Continued)

| Pin # | Name              | Description   |
|-------|-------------------|---|
| 9     | $\overline{Q0}$   | Output clock 0 (complement).  |
| 10    | Q0                | Output clock 0.   |
| 11    | NC                | No connect.   |
| 12    | V <sub>DD</sub>   | Core voltage supply.<br>Bypass with a 1.0 $\mu$ F capacitor placed as close to the pin as possible.   |
| 13    | NC                | No connect.   |
| 14    | CLK0              | Input clock 0.  |
| 15    | $\overline{CLK0}$ | Input clock 0 (complement).<br>When the CLK0 is driven by a single-end LVCMOS input, connect $\overline{CLK0}$ to V <sub>DD</sub> /2.<br>$\overline{CLK0}$ contains an internal pull-up resistor.   |
| 16    | OEA               | Output enable—Bank A.<br>When OEA = high, the Bank A outputs are enabled.<br>When OEA = low, Q is held low and $\overline{Q}$ is held high for differential formats.<br>For LVCMOS, both Q and $\overline{Q}$ are held low when OEA is set low.<br>OEA contains an internal pull-up resistor. |
| 17    | V <sub>REF</sub>  | Reference voltage for single-ended CMOS clocks.<br>V <sub>REF</sub> is an output voltage and is equal to V <sub>DD</sub> /2. It can be used to bias the /CLK input for single ended input clocks. See Section 2.3 for more details.   |
| 18    | OEB               | Output enable—Bank B.<br>When OEB = high, the Bank B outputs are enabled.<br>When OEB = low, Q is held low and $\overline{Q}$ is held high for differential formats.<br>For LVCMOS, both Q and $\overline{Q}$ are held low when OEB is set low.<br>OEB contains an internal pull-up resistor. |
| 19    | CLK1              | Input clock 1.  |
| 20    | $\overline{CLK1}$ | Input clock 1 (complement).<br>When the CLK1 is driven by a single-end LVCMOS input, connect $\overline{CLK1}$ to V <sub>DD</sub> /2.<br>$\overline{CLK1}$ contains an internal pull-up resistor.   |
| 21    | NC                | No connect.   |
| 22    | GND               | Ground.   |
| 23    | CLK_SEL           | MUX input select pin (LVCMOS).<br>When CLK_SEL is high, CLK1 is selected.<br>When CLK_SEL is low, CLK0 is selected.<br>CLK_SEL contains an internal pull-down resistor.   |
| 24    | $\overline{Q9}$   | Output clock 9 (complement).  |
| 25    | Q9                | Output clock 9.   |
| 26    | $\overline{Q8}$   | Output clock 8 (complement).  |

Table 24. Si53312 44-Pin QFN Descriptions (Continued)

| Pin #   | Name            | Description   |
|---------|-----------------|---|
| 27      | Q8              | Output clock 8.   |
| 28      | NC              | No connect.   |
| 29      | $\overline{Q7}$ | Output clock 7 (complement).  |
| 30      | Q7              | Output clock 7.   |
| 31      | SFOUTB[0]       | Output signal format control pin for Bank B.<br>Three-level input control. Internally biased at $V_{DD}/2$ . Can be left floating or tied to ground or $V_{DD}$ . |
| 32      | SFOUTB[1]       | Output signal format control pin for Bank B.<br>Three-level input control. Internally biased at $V_{DD}/2$ . Can be left floating or tied to ground or $V_{DD}$ . |
| 33      | DIVB            | Output divider configuration bit for Bank B.<br>Three-level input control. Internally biased at $V_{DD}/2$ . Can be left floating or tied to ground or $V_{DD}$ . |
| 34      | $V_{DDOB}$      | Output Clock Voltage Supply—Bank B (Outputs: Q5 to Q9).<br>Bypass with a 1.0 $\mu$ F capacitor placed as close to the pin as possible.                            |
| 35      | $\overline{Q6}$ | Output clock 6 (complement).  |
| 36      | Q6              | Output clock 6.   |
| 37      | $\overline{Q5}$ | Output clock 5 (complement).  |
| 38      | Q5              | Output clock 5.   |
| 39      | GND             | Ground.   |
| 40      | $\overline{Q4}$ | Output clock 4 (complement).  |
| 41      | Q4              | Output clock 4.   |
| 42      | $\overline{Q3}$ | Output clock 3 (complement).  |
| 43      | Q3              | Output clock 3.   |
| 44      | $V_{DDOA}$      | Output Voltage Supply—Bank A (Outputs: Q0 to Q4).<br>Bypass with a 1.0 $\mu$ F capacitor placed as close to the pin as possible.                                  |
| GND Pad | GND             | Ground Pad.<br>Power supply ground and thermal relief.  |

## 4. Ordering Guide

| Part Number  | Package | PB-Free, ROHS-6 | Temperature  |
|--------------|---------|-----------------|--------------|
| Si53312-B-GM | 44-QFN  | Yes             | –40 to 85 °C |

## 5. Package Outline

### 5.1. 7x7 mm 44-QFN Package Diagram

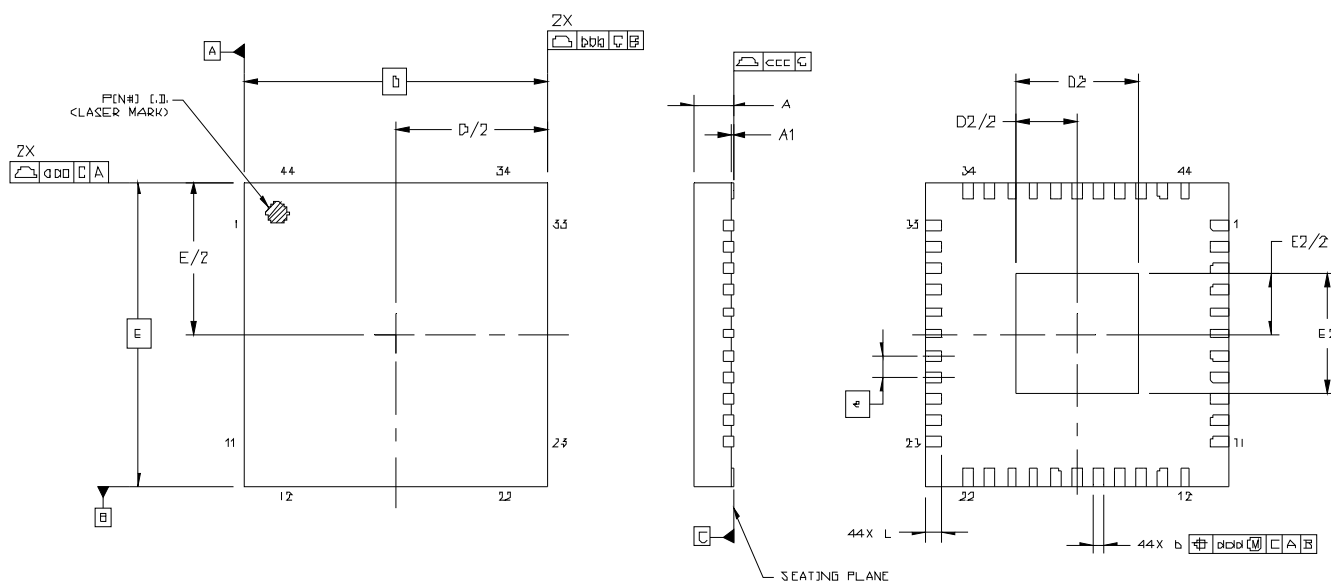


Figure 17. Si53312 7x7 mm 44-QFN Package Diagram

Table 25. Package Diagram Dimensions

| Dimension | MIN      | NOM  | MAX  |
|-----------|----------|------|------|
| A         | 0.80     | 0.85 | 0.90 |
| A1        | 0.00     | 0.02 | 0.05 |
| b         | 0.18     | 0.25 | 0.30 |
| D         | 7.00 BSC |      |      |
| D2        | 2.65     | 2.80 | 2.95 |
| e         | 0.50 BSC |      |      |
| E         | 7.00 BSC |      |      |
| E2        | 2.65     | 2.80 | 2.95 |
| L         | 0.30     | 0.40 | 0.50 |
| aaa       | —        | —    | 0.10 |
| bbb       | —        | —    | 0.10 |
| ccc       | —        | —    | 0.08 |
| ddd       | —        | —    | 0.10 |

**Notes:**

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. Dimensioning and Tolerancing per ANSI Y14.5M-1994.
3. This drawing conforms to the JEDEC Solid State Outline MO-220.
4. Recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.

## 6. PCB Land Pattern

### 6.1. 7x7 mm 44-QFN Package Land Pattern

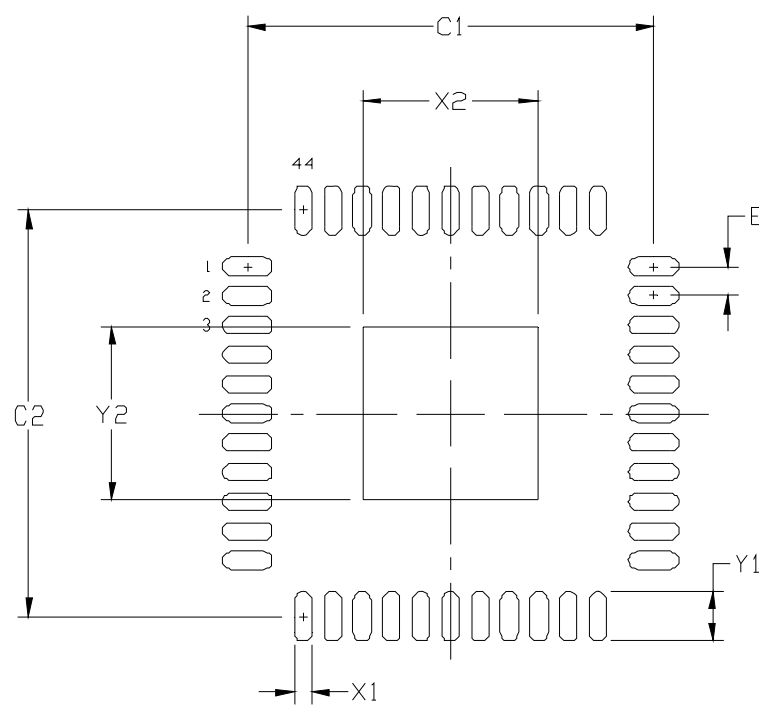


Figure 18. Si53312 7x7 mm 44-QFN Package Land Pattern

Table 26. PCB Land Pattern

| Dimension | Min      | Max  | Dimension | Min  | Max  |
|-----------|----------|------|-----------|------|------|
| C1        | 6.80     | 6.90 | X2        | 2.85 | 2.95 |
| C2        | 6.80     | 6.90 | Y1        | 0.75 | 0.85 |
| E         | 0.50 BSC |      | Y2        | 2.85 | 2.95 |
| X1        | 0.20     | 0.30 |           |      |      |

**Notes:**

**General**

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. This Land Pattern Design is based on the IPC-7351 guidelines.

**Solder Mask Design**

1. All metal pads are to be non-solder mask defined (NSMD). Clearance between the solder mask and the metal pad is to be 60  $\mu$ m minimum, all the way around the pad.

**Stencil Design**

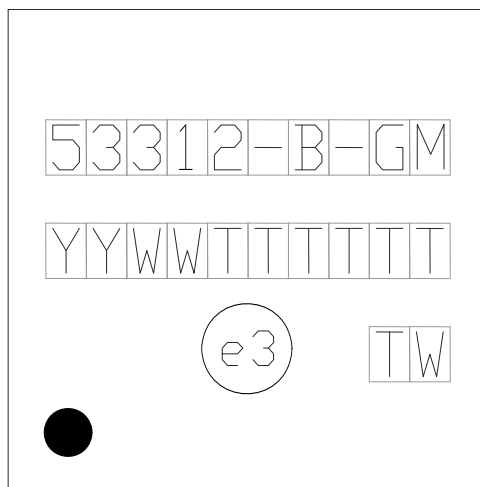
1. A stainless steel, laser-cut and electro-polished stencil with trapezoidal walls should be used to assure good solder paste release.
2. The stencil thickness should be 0.125 mm (5 mils).
3. The ratio of stencil aperture to land pad size should be 1:1 for all perimeter pads.
4. A 2x2 array of 1.0 mm square openings on 1.45 mm pitch should be used for the center ground pad.

**Card Assembly**

1. A No-Clean, Type-3 solder paste is recommended.
2. The recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.

## 7. Top Marking

### 7.1. Si53312 Top Marking



### 7.2. Top Marking Explanation

|                        |  |   |
|------------------------|--|---|
| <b>Mark Method:</b>    | Laser                                      |   |
| <b>Font Size:</b>      | 1.9 Point (26 mils)<br>Right-Justified     |   |
| <b>Line 1 Marking:</b> | Device Part Number                         | <b>53312-B-GM</b>   |
| <b>Line 2 Marking:</b> | YY=Year<br>WW=Work Week                    | Assigned by Assembly Supplier.<br>Corresponds to the year and work week of the mold date. |
|                        | TTTTTT=Mfg Code                            | Manufacturing Code from the<br>Assembly Purchase Order form.                              |
| <b>Line 3 Marking:</b> | Circle=1.3 mm Diameter<br>Center-Justified | "e3" Pb-Free Symbol   |
|                        | Country of Origin<br>ISO Code Abbreviation | <b>TW</b>   |
| <b>Line 4 Marking</b>  | Circle = 0.75 mm Diameter<br>Filled        | Pin 1 Identification  |

## DOCUMENT CHANGE LIST

### Revision 0.4 to Revision 1.0

- Updated frequency spec from 1MHz to dc.
- Updated operating conditions, including LVCMOS and HCSL voltage support.
- Updated tables 1-11.
- Fixed package error to reflect 44-pin instead of 32-pin throughout document.
- Updated section 2.1-2.12 text descriptions and diagrams.
- Improved data for additive jitter specifications.
- Improved typical phase noise plots.
- Improved performance specifications with more detail.



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